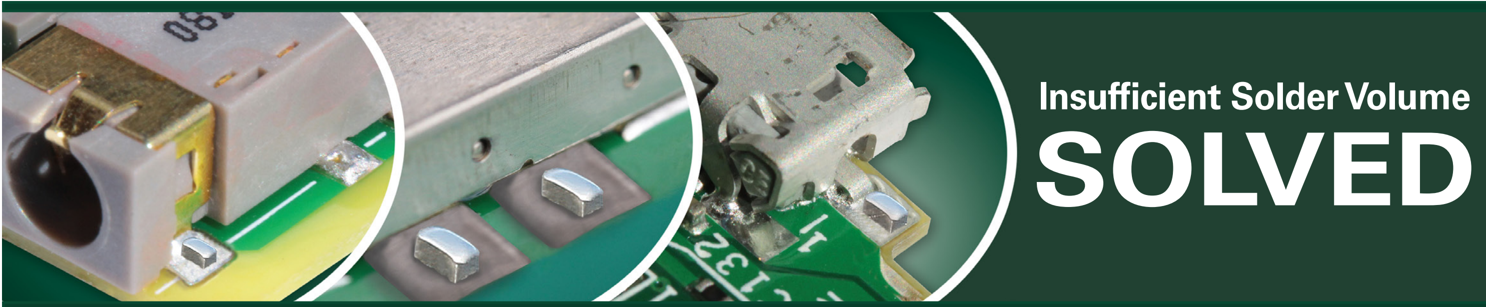
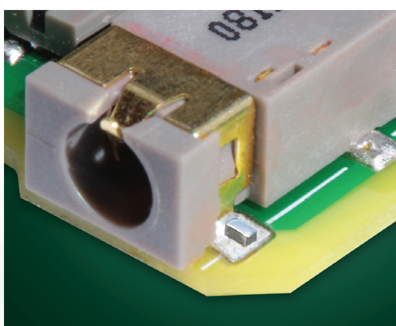
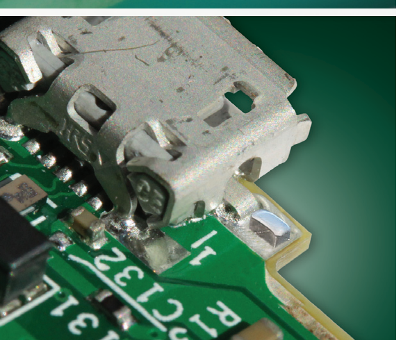


SOLDER FORTIFICATION®

INDIUM CORPORATION®

Add Solder Fortification® Preforms to:





Connectors: Improve reliability with added solder

RF Shields: Fortify connections; provide sufficient solder volume

- Thin stencils leave large deposits solder-starved
- Preforms add solder volume without modifying stencil design
- Multiple preforms can be placed in paste to add solder volume exactly where it is needed
- Preforms prevent failures from shock due to insufficient connections

Through-Hole Assemblies: Ensure complete hole fill

- Assemble through-hole parts reliably without wave soldering
- Paste alone will not provide complete hole fill since much of the solder paste volume is approximately 50% flux
- Add a preform to add solder without adding more flux
- Minimize flux pooling around these components
- Preforms allow optimal fillet formation

Myth: Only squared preforms can be used for Solder Fortification®

It is not true that only squared or flat-sided preforms can be used for solder fortification. In fact, even spheres have been used to add solder volume.

The key to success for using Solder Fortification® preforms is their ability to be pick and placed easily.

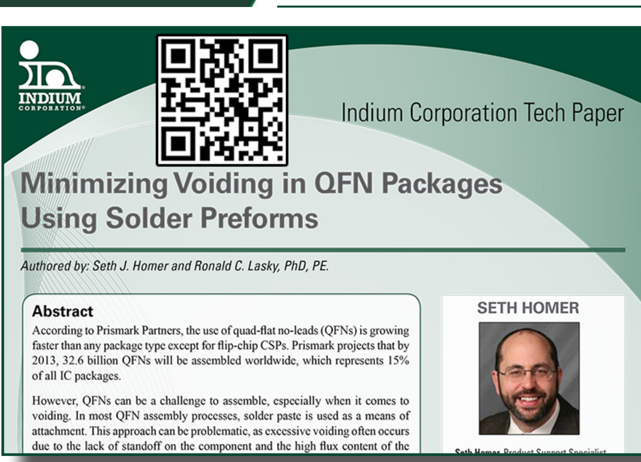
Indium Corporation is the leader in custom designed preforms. Although standard dimensions in tape are 0201, 0603, 0402, and 0805, we also offer custom solutions. Contact us and we will make sure you “pick” the right solution.

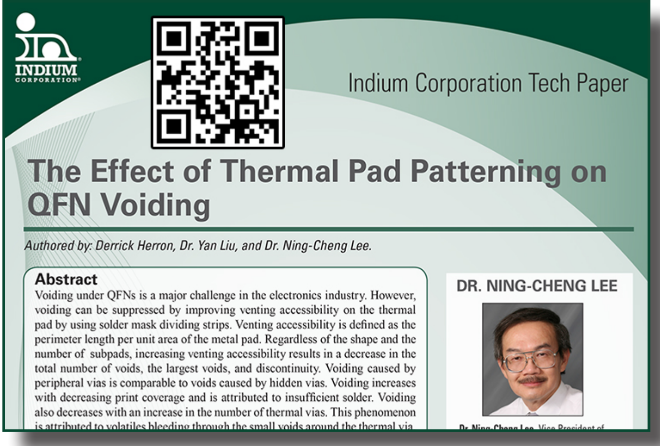
Solving SMT problems with Solder Preforms

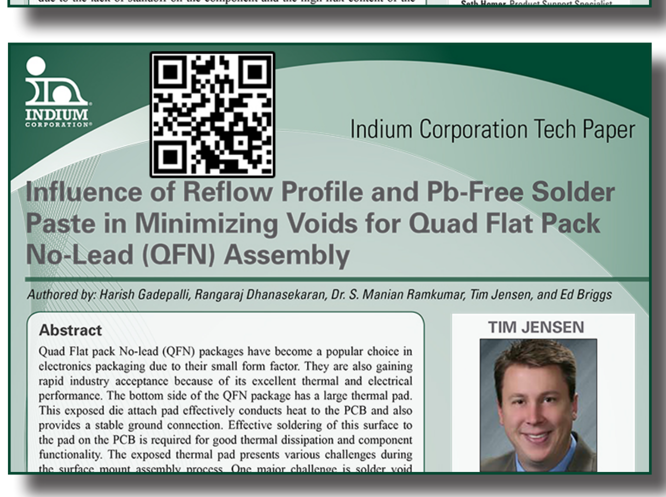
Need a solution to QFN voiding? We wrote the book.

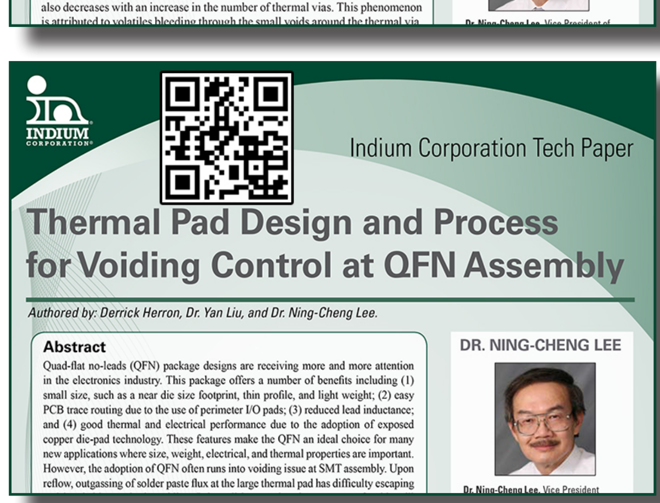
Check our tech papers online or contact us directly and speak to one of our tech service engineers.

From One Engineer to Another®









Form No. 98842 R0

www.indium.com **askus@indium.com**

ASIA: Singapore, Cheongju: +65 6268 8678
CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
USA: Utica, Clinton, Chicago: +1 315 853 4900

©2013 Indium Corporation